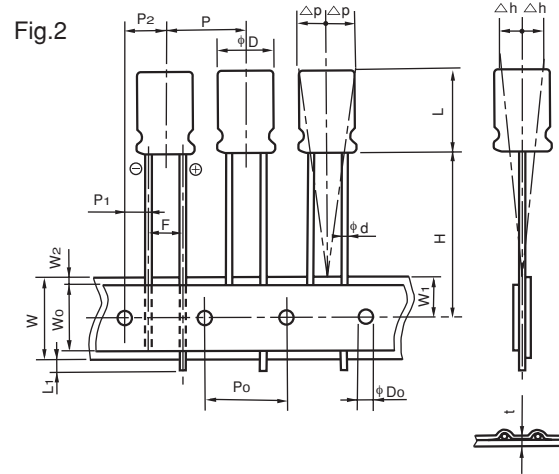
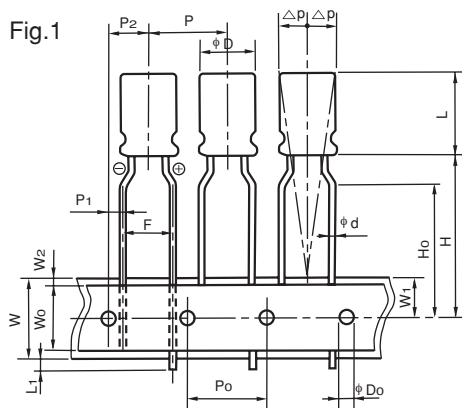
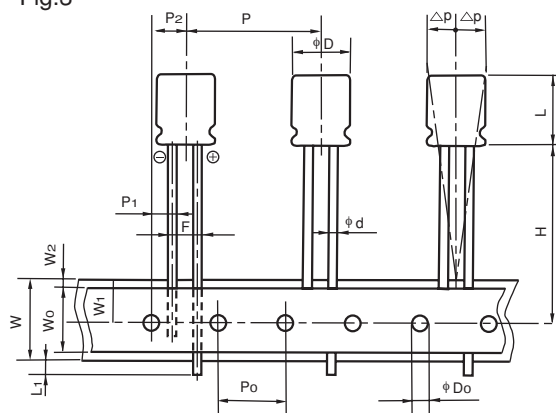


◆ TAPING SPECIFICATIONS
◆ DIMENSIONS

◆ SPECIFICATION TABLE

(mm)

Items	Code	5mm Height		7mm or 7.5mm Height				Tolerance
		φ 3~φ 8	φ 4~φ 6.3	φ 4~φ 6.3	φ 8			
Taping code		T5	TZ	T5	TZ	TA	T7	
Applicable Fig. No.		Fig.2	Fig.1	Fig.2	Fig.1	Fig.1	Fig.2	
Dia. of lead	φ d	0.4 or 0.45		0.45			±0.05	
Height of body	L	6.5		8.0			MAX	
Distance from center to center of next body	P	12.7		12.7			±1.0	
Distance from center to center of next driving hole	P ₀	12.7		12.7			±0.2	
Distance between center of driving hole and lead	P ₁	5.1	3.85	5.1	3.85	4.6	±0.5	
Distance between center of driving hole and body	P ₂	6.35		6.35			±1.0	
Pitch of lead	F	2.5	5.0	2.5	5.0	3.5	+0.8 -0.2	
Width of mounting tape	W	18.0		18.0			±0.3	
Width of adhesive tape	W ₀	5.0		5.0			MIN	
Distance between center of driving hole and mounting tape edge	W ₁	9.0		9.0			±0.5	
Max. allowable distance between mounting and adhesive tape edges	W ₂	1.5		1.5			MAX	
Distance between center of driving hole and bottom of body	H	17.5		17.5		20.0	±0.75	
Distance between center of driving hole and clinch part of lead	H ₀	—	16.0	—	16.0		±0.5	
End of lead	L ₁	0.5		0.5			MAX	
Dia. of driving hole	φ D ₀	4.0		4.0			±0.2	
Off alignment of body top	Δh	1.0		1.0			MAX	
Off alignment of body top	Δp	1.0		1.0			MAX	
Sum of thickness for mounting and adhesive tape without lead dia	t	0.6		0.6			±0.3	
Quantity (pcs)		2000 (φ 8:1000)						

Fig.3

◆ SPECIFICATION TABLE

(mm)

Items	Code	9mm or more Height						Tolerance	
		φ 5, φ 6.3	φ 8	φ 10	φ 12.5	φ 16	φ 18		
Taping code		T1	TA	TA	T7	T8	G4	GC	
Applicable Fig. No.		Fig.2	Fig.1	Fig.1	Fig.2	Fig.2	Fig.2	Fig.3	
Dia. of lead	φ d	0.5	0.6			0.8		±0.05	
Height of body	L	13.0	22.0	30.0	42.0		MAX		
Distance from center to center of next body	P	12.7			15.0	30.0	±1.0		
Distance from center to center of next driving hole	P ₀	12.7			15.0	15.0 ± 0.3	0.2		
Distance between center of driving hole and lead	P ₁	5.1	3.85	4.6	3.85	5.0	3.75	±0.5	
Distance between center of driving hole and body	P ₂	6.35			7.5		±1.0		
Pitch of lead	F	2.5	5.0	3.5	5.0 ± 0.8	7.5 ± 0.8		+0.8 -0.2	
Width of mounting tape	W	18.0						±0.3	
Width of adhesive tape	W ₀	5.0						MIN	
Distance between center of driving hole and mounting tape edge	W ₁	9.0						±0.5	
Max. allowable distance between mounting and adhesive tape edges	W ₂	1.5						MAX	
Distance between center of driving hole and bottom of body	H	18.5	20.0	18.5 ^{+0.75} _{-0.5}			0.75		
Distance between center of driving hole and clinch part of lead	H ₀	—	16.0	—	—			±0.5	
End of lead	L ₁	0.5						MAX	
Dia. of driving hole	φ D ₀	4.0						±0.2	
Off alignment of body top	△h	1.0						MAX	
Off alignment of body top	△p	1.0						MAX	
Sum of thickness for mounting and adhesive tape without lead dia	t	0.6						±0.3	
Quantity (pcs)		2000	1000	500	250				

◆ LEAD CUTTING FORMING SPECIFICATIONS

Rubycon provides lead-formed and lead-cut products to facilitate mounting on printed circuit boards, as well as products with leads specially processed (kink formed) for self supporting insertions to printed circuit boards.

• Lead forming
($\phi 5 \sim \phi 8$)
Lead forming code : FA

(mm)			
ϕD	5	6.3	8
ϕd	0.5		0.6
F	5.0		

• Lead cutting
($\phi 10 \sim \phi 18$)
Lead cutting code : CA
CC
CE

(mm)					
ϕD	10	12.5	14.5	16	18
H	5.0 (CA)				
	4.0 (CC)				
	3.5 (CE)				
ϕd	0.6		0.8		
F	5.0		7.5		

• Kinked lead forming
($\phi 5 \sim \phi 8$)
Kinked lead forming code : KC

• Kinked lead cutting
($\phi 10 \sim \phi 18$)
Kinked lead cutting code : KC

(mm)									
ϕD	5	6.3	8	10	12.5	14.5	16	18	
H1	4.5								
H2	2.8								
H3	2.5		—						
F	5.0				7.5				
P	1.0								
E	1.2			1.3					
ϕd	0.5		0.6			0.8			

• Low profile with horizontal mounting ($\phi 10 \sim \phi 18$)

(mm)								
ϕD	10, 12.5				14.5, 16, 18			
Code	RI	RK	RX	SG	RI	RK	RX	SG
ϕd	0.6				0.8			
F	5.0				7.5			
H	4.0		3.5		4.0		3.5	
Type	A	B	A	B	A	B	A	B